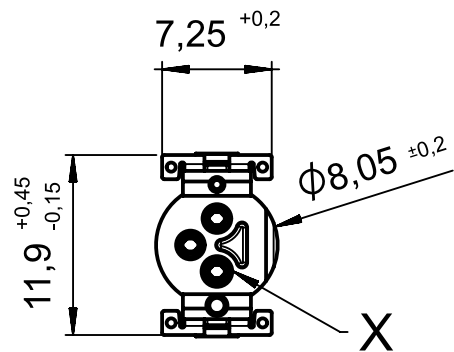
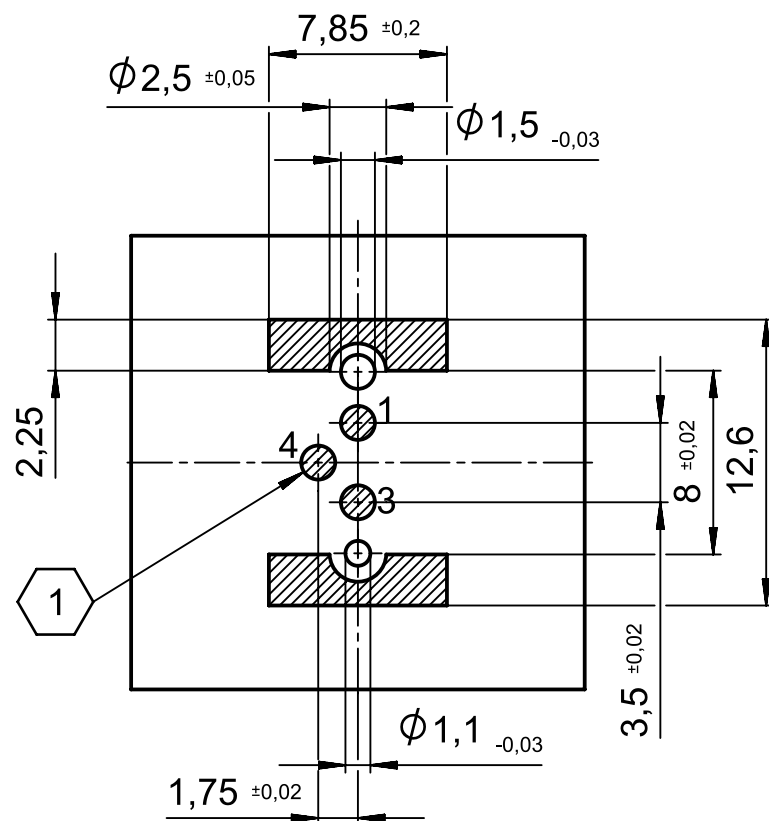


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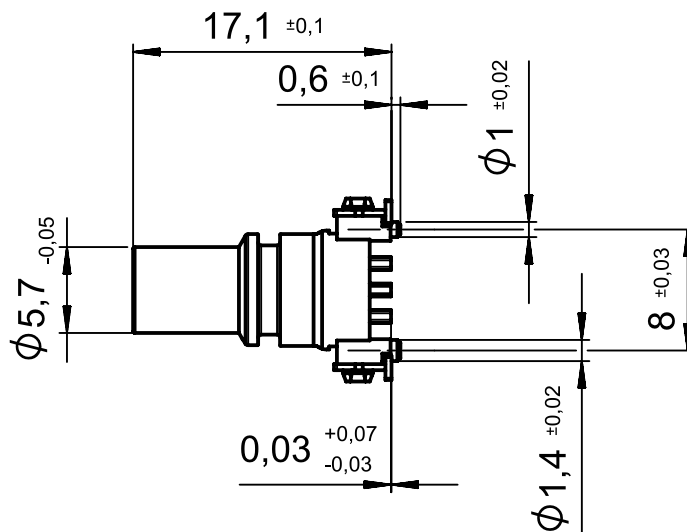
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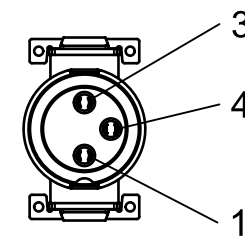
PCB-layout
(advice)



3:1

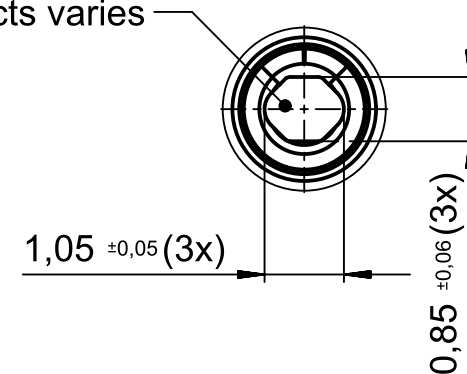


socket face female



X 10:1

orientation of the contacts varies



Coplanarity of all contacts and anchor plate  0.1

Recommended solder paste thickness 150µm

1 Further information on soldering process and recommended layout,
see brochure "Connectors for SMT production"

- EN ISO 291 23/50

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